JG® Techology

PRODUCT DATA SHEET

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Datasheet **Resources** **Samples**

General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

BVDSS	RDSON	ID
55V	1.2Ω	0.3A

Features

- *55V,0.3A, RDS(ON) =1.2Ω@VGS=10V*
- *Improved dv/dt capability*
- *Fast switching*
- *Green Device Available*
- *G-S ESD Protection Diode Embedded*
- *ESD protected up to 2KV*

SOT-23 Pin Configuration
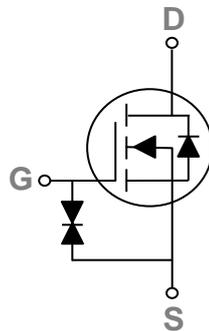
Applications

- *Motor Drive*
- *Power Tools*
- *LED Lighting*

Absolute Maximum Ratings Tc=25℃ unless otherwise noted

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	55	V
V_{GS}	Gate-Source Voltage	±20	V
I_D	Drain Current – Continuous (T_A=25℃)	0.3	A
	Drain Current – Continuous (T_A=70℃)	0.16	A
I_{DM}	Drain Current – Pulsed[1]	0.8	A
P_D	Power Dissipation (T_A=25℃)	0.35	W
	Power Dissipation – Derate above 25℃	0.003	W/℃
T_{STG}	Storage Temperature Range	-55 to 150	℃
T_J	Operating Junction Temperature Range	-55 to 125	℃

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{θJA}$	Thermal Resistance Junction to ambient	---	357	℃/W

Electrical Characteristics (T_J=25 ℃, unless otherwise noted)

Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS}=0V , I_D=250uA	55	---	---	V
I_{DSS}	Drain-Source Leakage Current	V_{DS}=55V , V_{GS}=0V , T_J=25℃	---	---	1	uA
		V_{DS}=40V , V_{GS}=0V , T_J=125℃	---	---	100	uA
I_{GSS}	Gate-Source Leakage Current	V_{GS}=±20V , V_{DS}=0V	---	---	±10	uA

On Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$R_{DS(ON)}$	Static Drain-Source On-Resistance	V_{GS}=10V , I_D=0.2A	---	1.2	1.5	Ω
		V_{GS}=4.5V , I_D=0.1A	---	1.5	2.5	Ω
$V_{GS(th)}$	Gate Threshold Voltage	V_{GS}=V_{DS} , I_D =250uA	0.8	1.1	1.5	V
gfs	Forward Transconductance	V_{DS}=10V , I_D=0.2A	---	0.5	---	S

Dynamic and switching Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Q_g	Total Gate Charge[2,3]	V_{DS}=30V , V_{GS}=10V , I_D=0.2A	---	3.7	---	nC
Q_{gs}	Gate-Source Charge[2,3]		---	0.9	---	
Q_{gd}	Gate-Drain Charge[2,3]		---	0.4	---	
$T_{d(on)}$	Turn-On Delay Time[2,3]	V_{DD}=30V , V_{GS}=10V , R_G=6Ω I_D=0.2A	---	3	---	ns
T_r	Rise Time[2,3]		---	5	---	
$T_{d(off)}$	Turn-Off Delay Time[2,3]		---	14	---	
T_f	Fall Time[2,3]		---	9	---	
C_{iss}	Input Capacitance	V_{DS}=30V , V_{GS}=0V , F=1MHz	---	25.5	---	pF
C_{oss}	Output Capacitance		---	17	---	
C_{rss}	Reverse Transfer Capacitance		---	7.8	---	

Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_S	Continuous Source Current	V_G=V_D=0V , Force Current	---	---	0.3	A
I_{SM}	Pulsed Source Current		---	---	0.6	A
V_{SD}	Diode Forward Voltage	V_{GS}=0V , I_S=0.2A , T_J=25℃	---	---	1.4	V
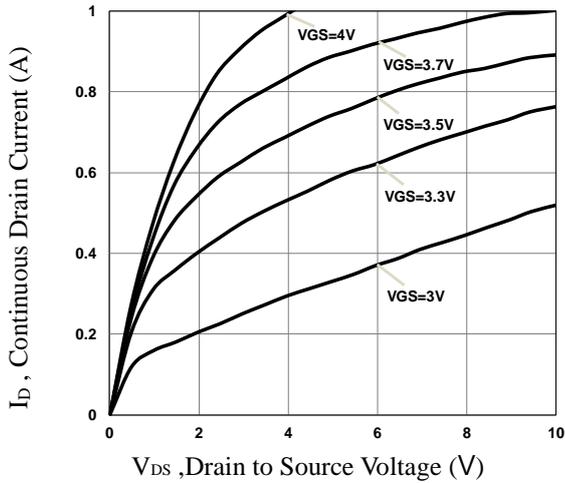
Fig.1   Typical Output Characteristics
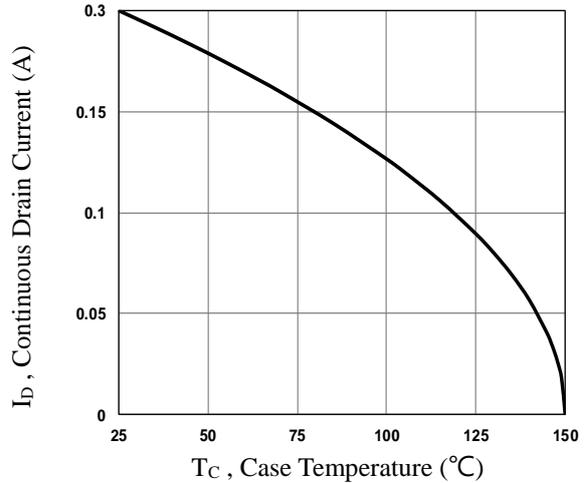
Fig.2   Continuous Drain Current vs. T_C
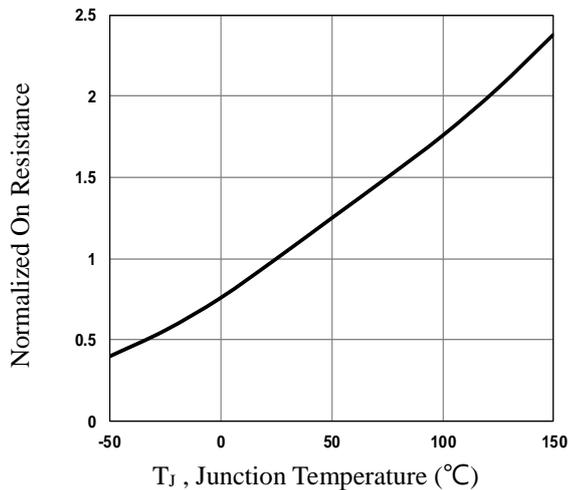
Fig.3   Normalized RDSON vs. T_J
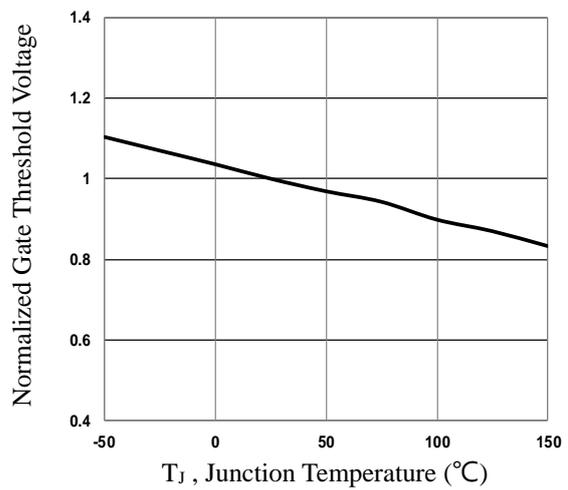
Fig.4   Normalized V_{th} vs. T_J
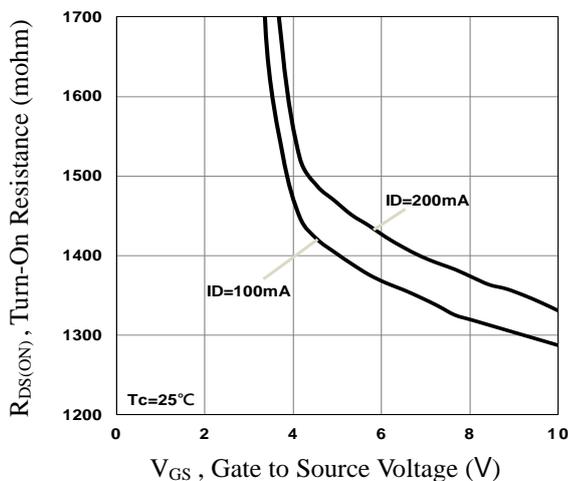
Fig.5   Turn-On Resistance vs. V_{GS}
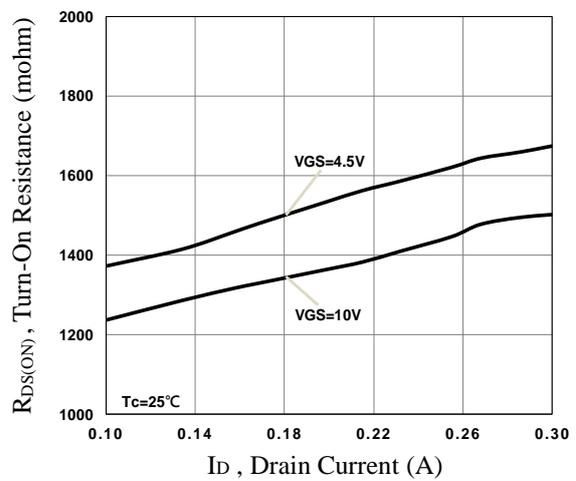
Fig.6   Turn-On Resistance vs. I_D
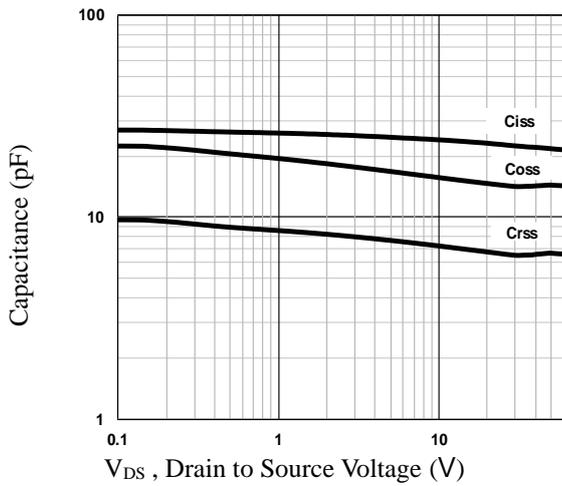
Fig.7　Capacitance Characteristics
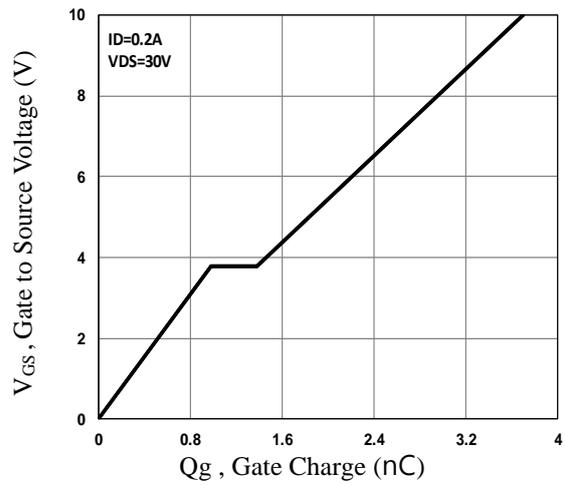
Fig.8　Gate Charge Characteristics
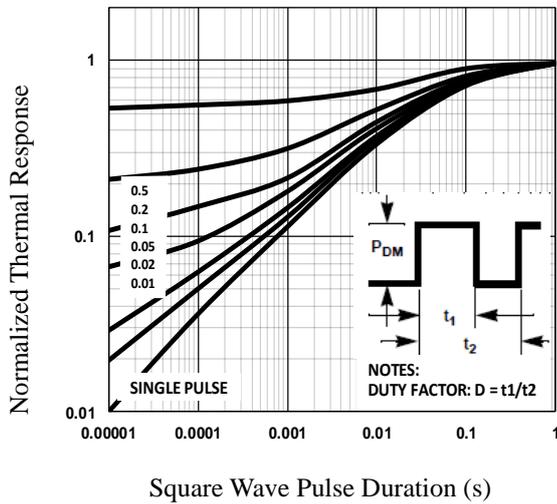
Fig.9　Normalized Transient
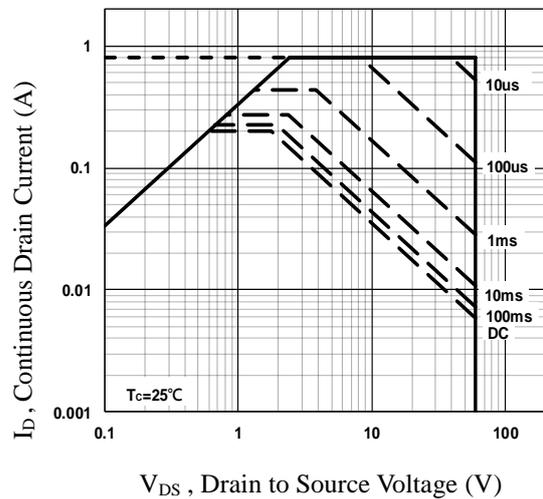
Fig.10　Maximum Safe Operation Area

SOT-23 PACKAGE INFORMATION
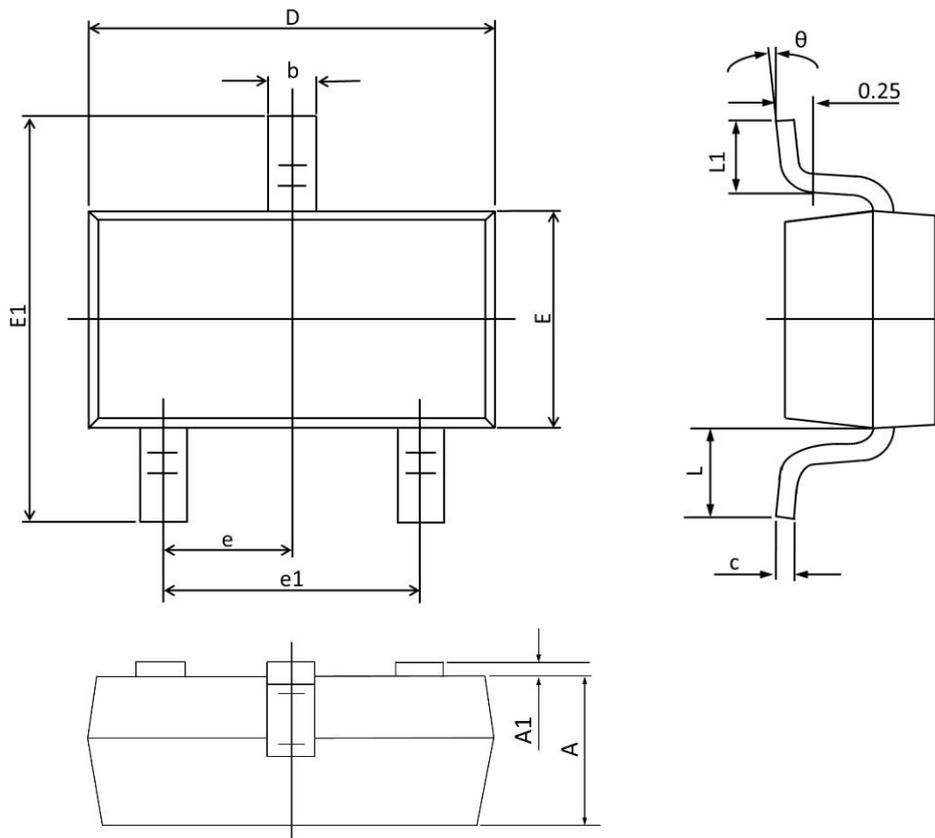
Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.150	0.035	0.045
A1	0.001	0.100	0.000	0.004
b	0.300	0.500	0.012	0.020
c	0.080	0.180	0.003	0.008
D	2.700	3.100	0.106	0.122
E	1.100	1.500	0.043	0.059
E1	2.100	2.640	0.080	0.104
e	0.950 TYP.		0.037 TYP.	
e1	1.780	2.040	0.070	0.080
L	0.550 REF.		0.022 REF.	
L1	0.100	0.500	0.004	0.020
θ	1°	10°	1°	10°

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